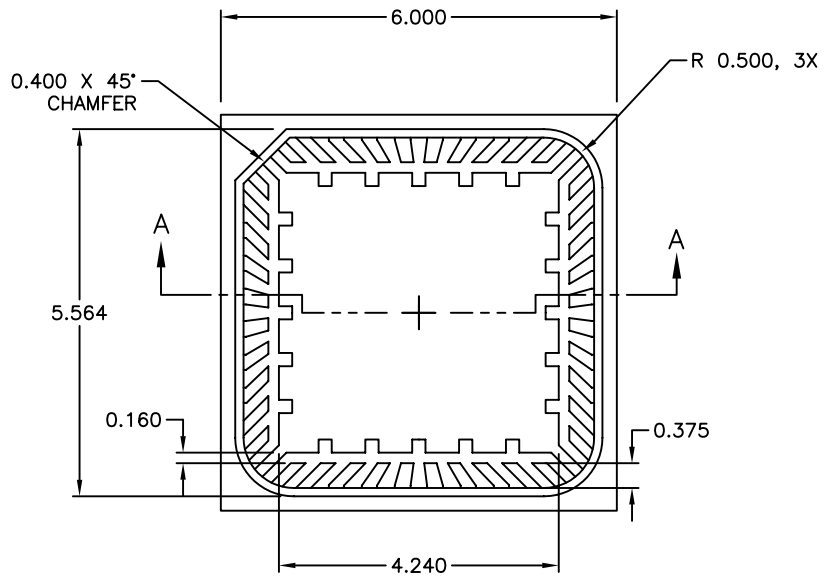
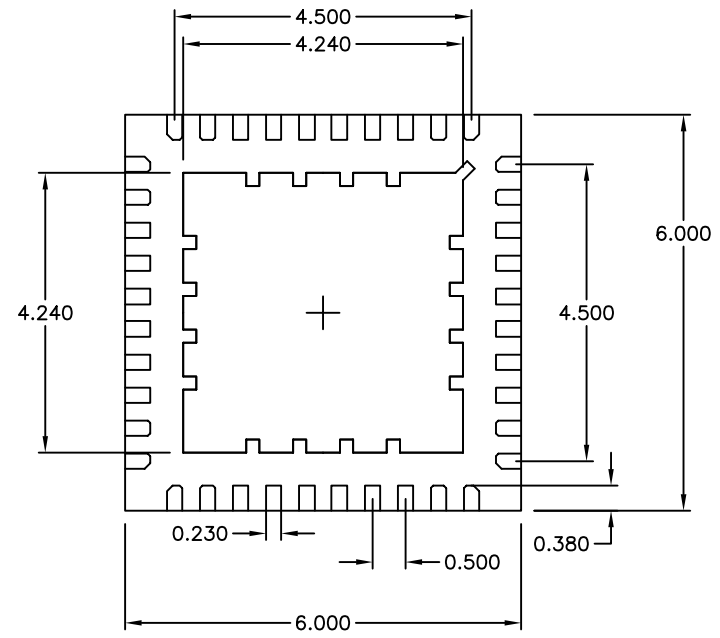
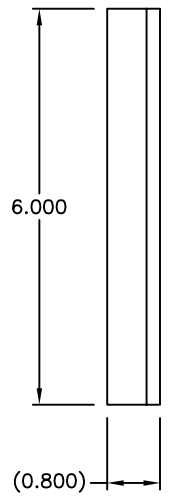


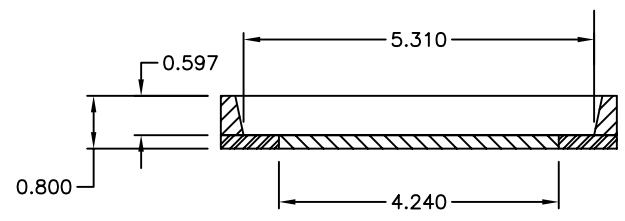
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
10627	3/20/06	PRODUCTION RELEASE	D.BENANDO



TOP VIEW



BOTTOM VIEW



SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FRAME: COPPER, 194 FH.
 3. LEAD FINISH: FULL GOLD PLATE.
 4. FRAME THICKNESS: 0.2030 ± 0.0076.
 5. DIE PAD: 4.240mm X 4.240mm.
 6. JEDEC OUTLINE: MO-220 (VJJD-5).

<p>THIRD ANGLE PROJECTION</p>	<p>DRAWN BY GRIFFITTS</p>	<p>DATE 3/19/06</p>
	<p>APP BY P. FLASKERUD</p>	<p>DATE 3/20/06</p>
<p>UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE:</p> <p>X.XX ± 0.015 X.XXXX ± ---</p> <p>X.XXX ± 0.050 ANGLES: ± 1°</p>	<p>CUSTOMER ---</p>	
<p>DO NOT SCALE DRAWING</p>		

<p>SEMPAC, INC. Open-Pak™ Technologies www.sempac.com 568 E. WEDDELL DRIVE, SUITE 5 SUNNYVALE, CALIFORNIA 94089 PHONE: (408) 400-9002 FAX: (408) 400-9006</p>			
<p>40 Lead 6mm x 6mm MLP Open-Pak</p>			
<p>SIZE A</p>	<p>PART NO. MLP6X6-40-OP-01</p>	<p>REV 1</p>	
<p>SCALE NONE</p>	<p>CAD FILE MLP6X6-40-OP-01-R1.DWG</p>	<p>SHEET 1 OF 1</p>	